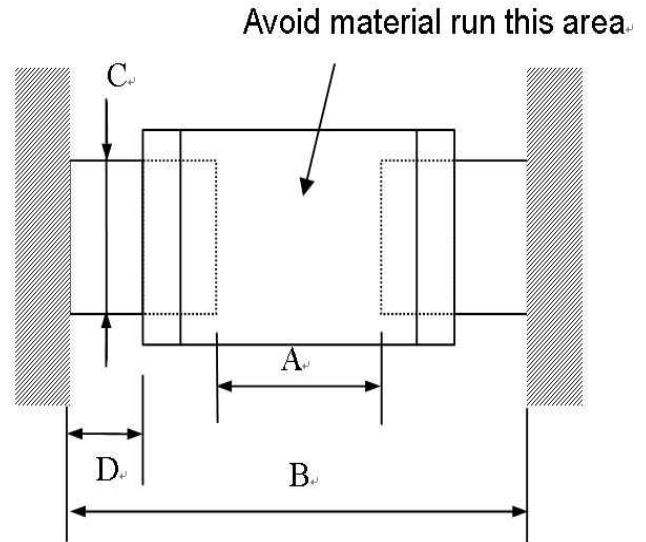


● **Soldering Recommendations**

1. Recommended solder pad layout

(Unit : mm)

	A	B	C	D
0402	0.4~0.6	1.6~1.8	0.5~0.6	0.2~0.4
0603	0.8~1.2	2.5~3.0	0.6~1.0	0.3~0.6
0805	1.0~1.5	3.2~3.8	1.2~1.4	0.3~0.6
1206	1.8~2.5	4.2~5.8	1.2~1.6	0.4~0.8
1210	1.8~2.5	4.2~5.8	1.8~2.5	0.5~1.0
1812	2.5~3.5	5.5~6.1	2.3~3.2	0.6~1.1
2220	3.5~4.6	6.0~7.2	4.8~5.5	1.2~2.3



2. The solder paste shall be printed in a thickness of 150 to 200µm.

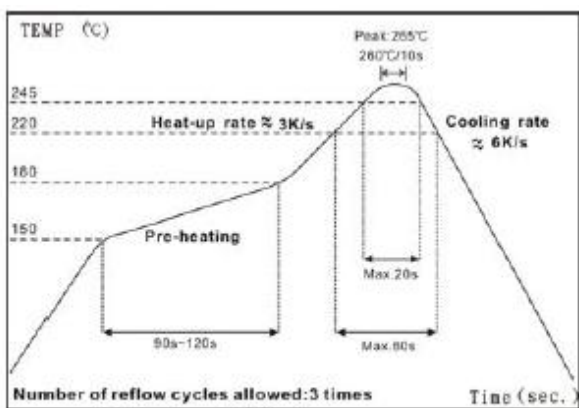
3. Recommended solder paste Sn/Ag/Cu (96/3.5/0.5) or equivalent.

4. Perform adequate test in advance as the reflow temperature profile will vary according to the conditions of the manufacturing process.

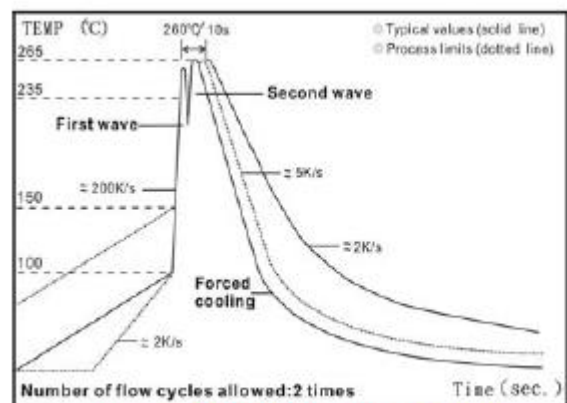
(1) Time of IR reflow soldering at maximum temperature point 260°C : 10s

(2) Time of wave soldering at maximum temperature point 260°C : 10s

(3) Time of soldering iron at maximum temperature point 410°C : 5s



IR Reflow Soldering



Wave Soldering (Flow Soldering)